

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A wiring board comprising:
a conductor layer comprising Fe and Cu; and
at least one of a radiator, a connection terminal, a cover and a circuit component,
connected to the conductor layer through a joining member,
which ~~is~~ wiring board ~~is~~ obtained by coating a copper paste comprising a copper powder,
an organic vehicle and an Fe_2O_3 particle mainly comprising Fe_2O_3 as a conductor layer on a
ceramic green sheet, and simultaneously firing the ceramic green sheet and coated copper paste.
2. (original): The wiring board according to claim 1, wherein a surface of the
conductor layer is subjected to a plating treatment.
3. (canceled)
4. (previously presented): The wiring board according to claim 1, wherein the
copper paste comprises more than 20 parts by mass of the organic vehicle per 100 parts by mass
of the copper powder.
5. (previously presented): The wiring board according to claim 1, wherein the
copper paste comprises a ceramic particle having an average particle size of 100 nm or less.

6. (previously presented): The wiring board according to claim 1, which is obtained by a method comprising the steps of

coating the copper paste on a ceramic green sheet;

exposing the coated sheet to a wet nitrogen atmosphere at 650 to 900°C so as to remove organic components; and

simultaneously firing the ceramic green sheet and coated copper paste at 850 to 1,050°C after the exposing.

7. (currently amended): A copper paste comprising a copper powder, an organic vehicle and an Fe_2O_3 particle mainly comprising Fe_2O_3 .

8. (original): The copper paste according to claim 7, wherein the copper paste comprises more than 20 parts by mass of the organic vehicle per 100 parts by mass of the copper powder.

9. (original): The copper paste according to claim 7, which comprises a ceramic particle having an average particle size of 100 nm or less.

10. (new): The wiring board according to claim 1, wherein said Fe_2O_3 particle has an average particle size of 1 μm or less.

11. (new): The copper paste according to claim 7, wherein said Fe_2O_3 particle has an average particle size of 1 μm or less.